T-1 (3mm) RIGHT ANGLE LED INDICATOR

Part Number: WP934EW/SRD Super Bright Red

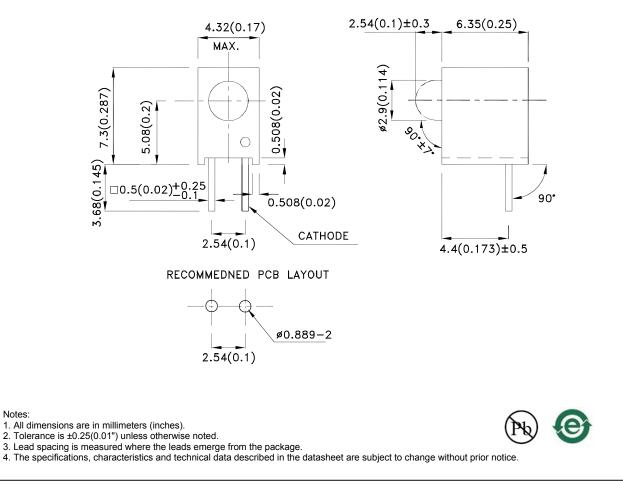
Features

- Pre-trimmed leads for pc mounting.
- Black case enhances contrast ratio.
- High reliability life measured in years.
- Housing UL rating:94V-0.
- Housing material: type 66 nylon.
- RoHS compliant.

Description

The Super Bright Red source color devices are made with Gallium Aluminum Arsenide Red Light Emitting Diode.

Package Dimensions



SPEC NO: DSAF1857 APPROVED: WYNEC REV NO: V.5A CHECKED: Allen Liu DATE: MAR/28/2013 DRAWN: F.Cui PAGE: 1 OF 5 ERP: 1102013069

Selection Guide lv (mcd) [2] Viewing @ 20mA Angle [1] Part No. Dice Lens Type 201/2 Min. Тур. 150 400 40° WP934EW/SRD Super Bright Red (GaAlAs) Red Diffused *100 *50

Notes:

1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

Luminous intensity/ luminous Flux: +/-15%.
* Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Red	655		nm	I⊧=20mA
λD [1]	Dominant Wavelength	Super Bright Red	640		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Red	20		nm	I⊧=20mA
С	Capacitance	Super Bright Red	45		pF	V⊧=0V;f=1MHz
VF [2]	Forward Voltage	Super Bright Red	1.85	2.5	V	I⊧=20mA
IR	Reverse Current	Super Bright Red		10	uA	VR = 5V

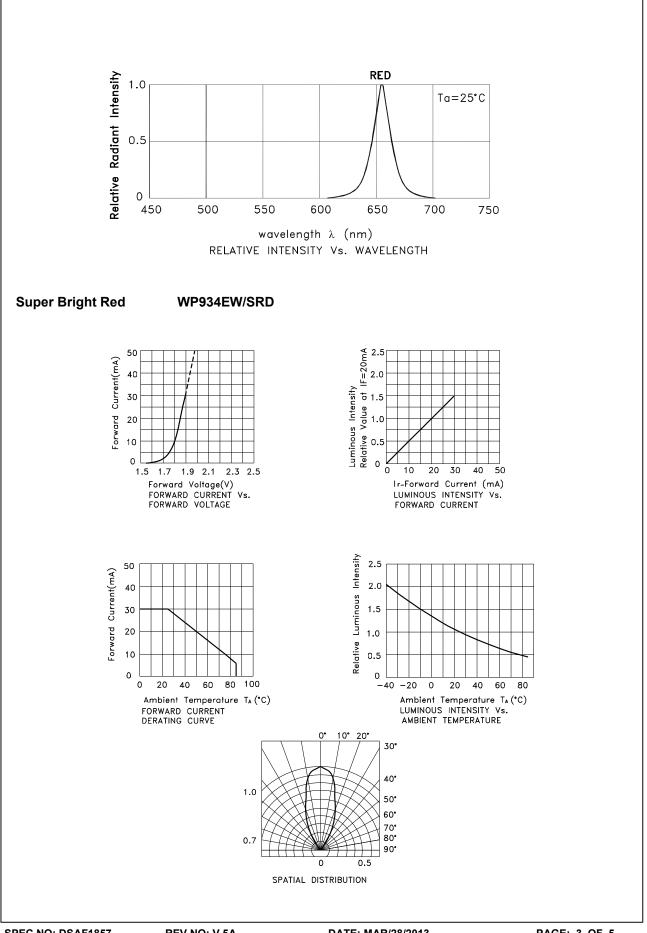
Notes: 1.Wavelength: +/-1nm. 2.Forward Voltage: +/-0.1V. 3.Wavelength value is traceable to the CIE127-2007 compliant national standards.

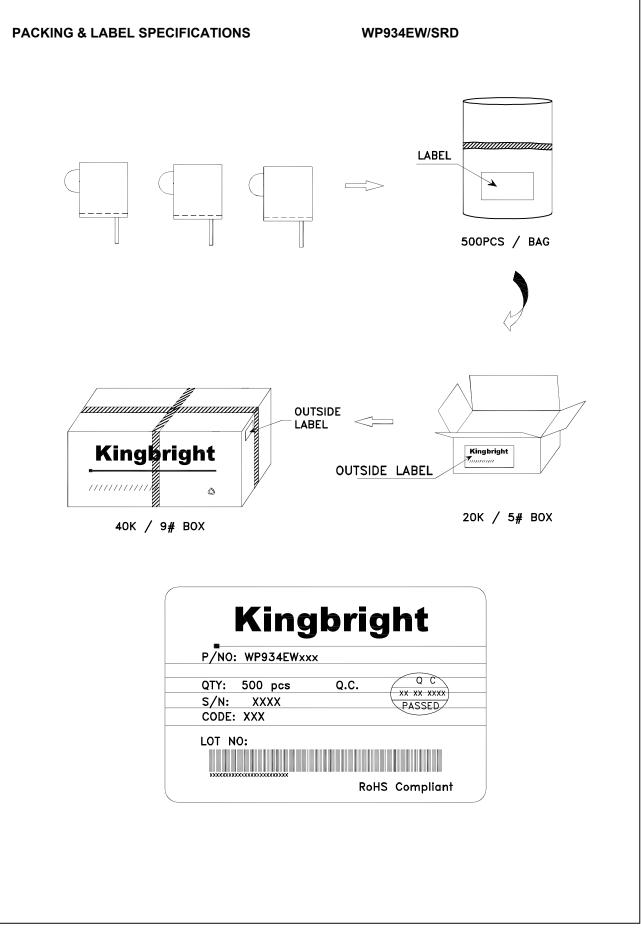
Absolute Maximum Ratings at TA=25°C

Parameter	Super Bright Red			
Power dissipation	75			
DC Forward Current	30	mA		
Peak Forward Current [1]	155	mA		
Reverse Voltage	5	V		
Operating/Storage Temperature	-40°C To +85°C			
Lead Solder Temperature [2]	260°C For 3 Seconds			
Lead Solder Temperature [3]	260°C For 5 Seconds			

Notes:

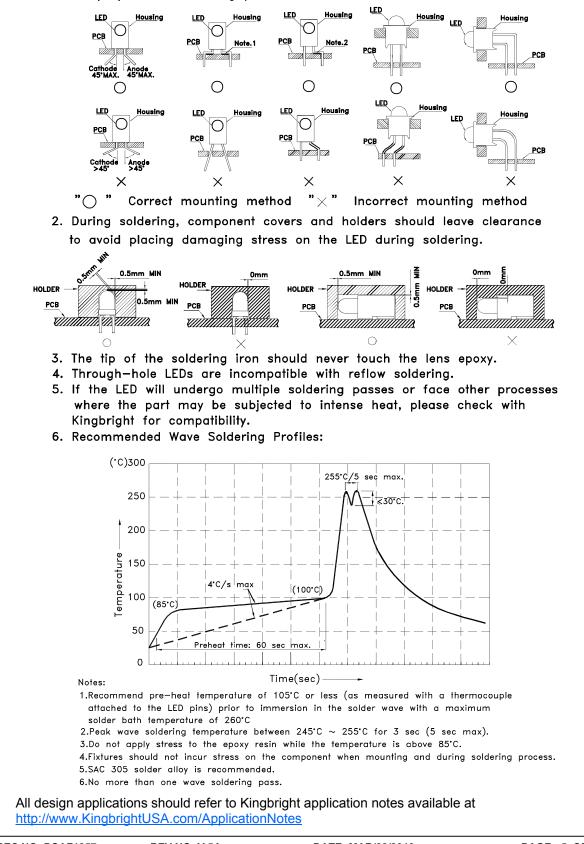
1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. 2mm below package base.
3. 5mm below package base.





PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.



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